

IN THE ABSTRACT:

The Abstract as amended below shows added text with underlining and deleted text with ~~strikethrough~~. Please amend the Abstract in accordance with the following:

ABSTRACT OF THE DISCLOSURE

~~A conventional semiconductor package can be used as it is, further an additional function such as a~~ A capacitor can be ~~is~~ arranged at the closest position to a semiconductor element and the generation of switching noise ~~can be~~ is reduced as low as possible ~~under the conditions of~~ by increasing the processing speed, arranging the components highly intensively and reducing the operation voltage. One face of the capacitor (30) is connected to an electrode of the electrode forming face of the semiconductor element (40) and the other face of the capacitor is connected to the connection pads on the wiring board so that the capacitor ~~can be~~ is interposed between the electrode forming face of the semiconductor element and the semiconductor mounting face of the wiring board (20), the other face of the capacitor is connected to the connection pads on the wiring board, and at the same time, flip-chip connection is conducted on the connection pads on the wiring board via the solder bumps (35) ~~which have already been~~ connected to the electrodes of the semiconductor element.